



天弘激光
TIANHONG LASER

Small and Medium Power Laser Equipment Brochure

Precision Laser Cutting / Laser Resistor Trimming / Silver Paste Etching / Laser Marking / Laser Wire Stripping



BETTER TIANHONG
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CATALOG

■ Company Profile	03
■ Semiconductor industry series equipment.....	07
Wafer Laser Cutting Machine	08
Wafer Laser Cutting Machine	09
Full Automatic Wafer Laser Cutting Machine	10
Full Automatic Wafer Laser Cutting Machine.....	11
Wafer Laser Marking Machine	12
Automatic Wafer Edge Stripping Machine	13
■ New energy industry series equipment.....	14
Film Solar Cell Edge Laser Cleaning Machine.....	15
Film Solar Cell Laser Processing Equipment	16
■ Display industry series devices	17
Film Cutting Machine	18
CO2 Laser Die Cutting Machine	19
ITO Laser Etching Machine	20
Multi-head ITO Laser Etching Machine	21
Green Light Glass Laser Drilling Machine	22
Infrared Picosecond Glass Laser Drilling Machine	23
Infrared Picosecond Laser Wire Cutting Machine	24
Filter Laser Cutting Equipment	25
■ FPC/PCB series equipment	26
UV Laser Cutting Machine	27
Picosecond UV Laser Cutting Machine.....	28
■ Marking industry series equipment.....	29
Fiber Laser Marking Machine	30
UV Laser Marking Machine	31
CO2 Laser Marking Machine	32
PCB Automatic Double Sided Laser Marking System.....	33
Flying Laser Marking Machine	35
Nameplate Automatic Laser Marking Machine.....	36
Laser Wire/Cable Stripping Machine.....	37
Cylindrical Laser Marking Machine	38
Bearing Laser Marking Machine	39
Laser Cleaning Machine	40
Mini Laser Marking Machine	41
Five Axis 3D Marking System (LDS).....	42
Laser Resistor Trimming System	43
Invar Laser Processing System	44
■ Enterprise Honor	45



Suzhou Tianhong Laser Co., Ltd. is a global leading integrated laser solutions provider, founded in January 2001, with a registered capital of 72.32 million yuan and more than 70,000 square feet of property. There are six factories, one software company and one sub-brand company under the group, including Suzhou Tianhong headquarters, Suqian Tianhong, Zhejiang Tianhong, Guangdong Tianhong, Guangdong Xin Shijie, Zhangjiagang Collect, Suzhou Tianzuo Data and Suzhou ECO2 Laser; It has nine types of standardized intelligent equipment production bases, including: high power laser cutting, laser tube cutting, small and medium power laser processing, laser welding, laser micro (precision) processing, laser cladding (remufacturing), and laser welding, Laser micro (precision) processing, laser cladding (remufacturing), laser quenching (strengthening), laser 3D printing, laser automation production line, etc. Tianhong Laser focuses on the development, manufacturing and service of industrial intelligent equipment.

Our technologies cover: software, mechanical, electrical, motion control, robotics, laser, optics, image, material, laser process, etc.



Suzhou headquarter



Guangdong company



Zhejiang company



Suqian company



Company Showroom



Factory workshop

COMPANY PROFILE



- 2001** Suzhou Tianhong Laser Co., Ltd. established to carry out small and medium power laser marking business
- 2004** Start solid-state laser welding machine business
- 2007** Laser micromachining business starts, enter into semiconductor field
- 2008** Certified as "National High and New Technology Enterprise"; Awarded as "Jiangsu Private Technology Enterprise".
- 2009** Conducted laser cutting machine development; Joint-stock company officially established
- 2011** Certified as Suzhou Industrial Park "Double Hundred Project" science and technology enterprise; Awarded as Jiangsu famous trademark enterprise and Suzhou famous brand product enterprise; Started laser cladding cooperative development business
- 2012** Certified as "Jiangsu Province Laser 3D Forming and Microfabrication Engineering Technology Research Center"; Cooperated with Suzhou University to set up Jiangsu Province Enterprise Graduate Workstation; in October, the company's new factory was completed.
- 2013** Completed the acceptance of the 12th Five-Year Plan 863 Project of the Ministry of Science and Technology "High Power and Picosecond Laser Industrialization Application Demonstration"; Started the business of intelligent automated robot production line
- 2014** Listed on the New Third Board of the National Stock Exchange System; "Tianzuo Data" subsidiary established
- 2015** Acquired Collect to start 3D printing remanufacturing service, acquired CO2 laser business; Certified as Jiangsu Province's two integration demonstration pilot enterprise
- 2016** Selected as one of the "Gazelle Plan" enterprises in Suzhou; "OFweek 2016 Most Growing Laser Enterprise" award; awarded the "Star of Entrepreneurial Leadership" award by the New Third Board to establish a high-power high-speed cutting team
- 2017** Subsidiary Hengfast Laser (mass production of CO2 lasers); Tianhong Laser (Suqian) was established; certified as "Most Growing High-tech Enterprise"; certified as "Suzhou Top 100 Specialized and New Enterprise"; Certified subsidiary Tianzuo as "Software Enterprise"
- 2018** Selected as one of the "Gazelle Plan" enterprises in Suzhou Industrial Park
- 2019** Selected as an excellent demonstration enterprise of science and technology innovation in Jiangsu Province
- 2020** Tianhong Laser (Guangdong) company established; Zhejiang Tianhong company established; Guangdong Xinshijie Power Technology Co., Ltd. was established.
- 2021** Zhejiang Lin Mu Automation Technology Co.Ltd established;Zhejiang Tianhong Laser Technology Co.Ltd officially put into establishment

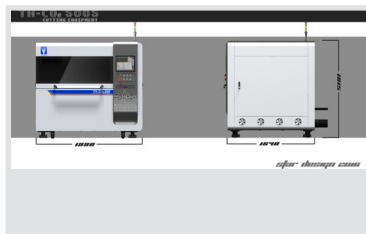
CORPORAT STYLE



The equipment is exported to more than 30 countries and regions
With 4 R&D and production bases



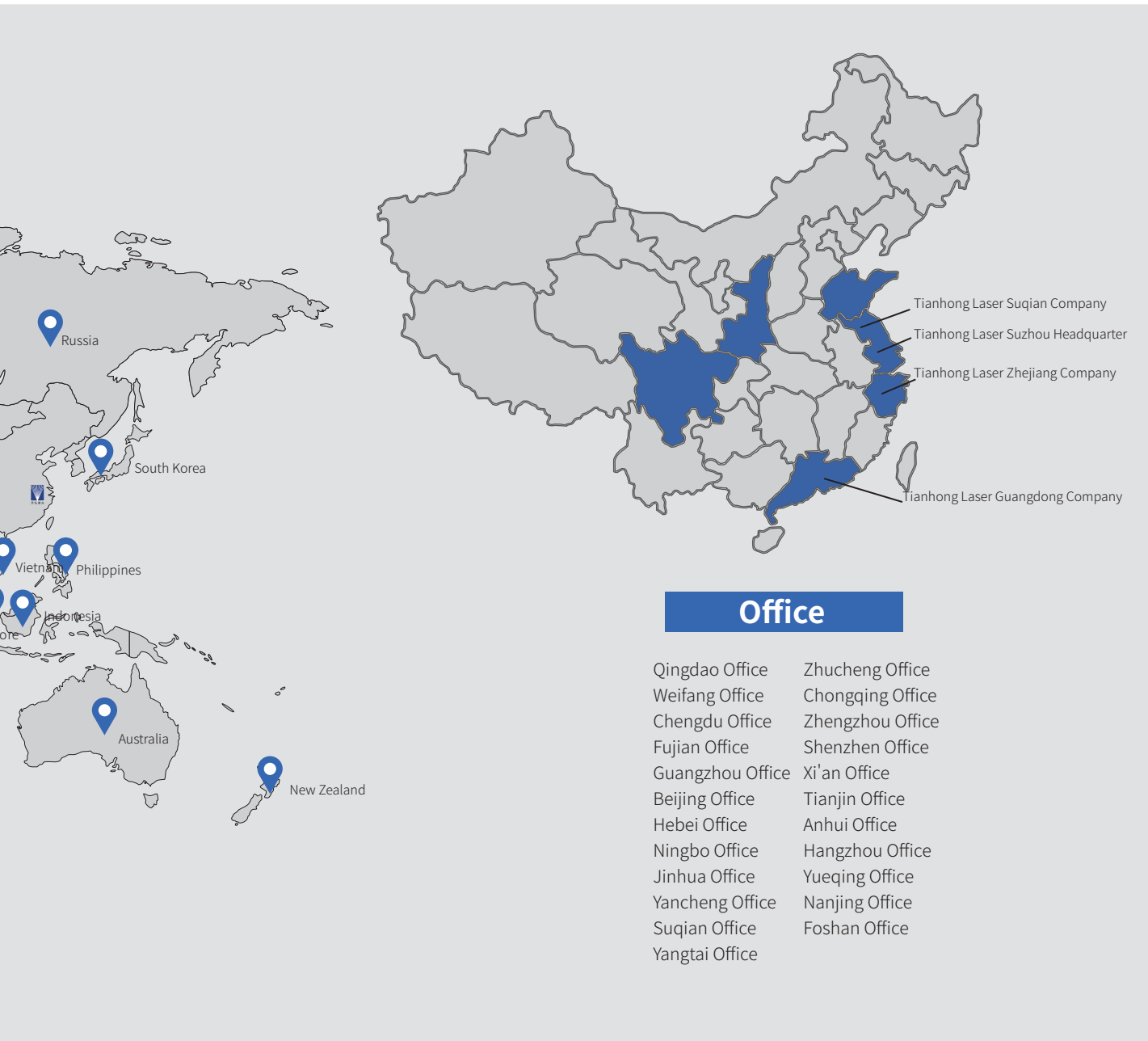
Malaysia customer visit



Marketing activity



Company reunion



Municipal committee leaders inspection



Industrial park leadership inspection



863 project acceptance

Semiconductor industry series equipment

BETTER TIANHONG BETTER LASER

Wafer Laser Cutting Machine

Features

- » High scribing speed with high efficiency and low defective rate
- » Non-contact processing without mechanical stress, thus improving wafer quality
- » CCD high speed positioning, real-time coaxial or paraxial monitoring function
- » High accuracy 2D linear motion platform and high accuracy DD rotation platform
- » Marble base with high stability and low thermal deformation
- » CNC control
- » Friendly interface and easy to operate
- » Scribing technology expert system
- » High reliability and stability
- » Equipped with automatic splitting equipment, easy to operate with high efficiency

Application field

Widely used in the scribing of integrated circuit wafers, GPP wafers and TVS wafers.



Technical Parameter

Model	TH-5212	TH-5221	TH-5210
Laser source	IR	IR	UV
Wavelength	1064nm	1064nm	355nm
Laser power	20w/30w	20w/30w	5w/10w/17w
Max. Wafer dimension	5 inch (6inch compatible)	4 inch	4 inch
Scribing speed	150mm/s、200mm/s	150mm/s、200mm/s	30mm/s、60mm/s、100mm/s
Line width	35~45μm	40~50μm	20~30μm
Line depth	< 120μm (depending on material)	50 -120μm	50-100μm
Positioning accuracy	±5μm	±5μm	±5μm
Repositioning accuracy	±2μm	±2μm	±2μm
Laser service life	100,000 hours	100,000 hours	12,000 hours
Dimension	960*730*1740mm	960*730*1740mm	960*730*1740mm
Total weight	660kg	660kg	660kg

Wafer Laser Cutting Machine

Features

- » This equipment is a high-end automatic slicing equipment mainly developed for GPP wafers, equipped with double-sided CCD recognition function
- » CCD function solves the process that traditional equipment needs to etch line grooves on the back of the wafer for alignment cutting, and can be cut without back grooves
- » At the same time, it can integrate the CCD alignment wafer backside etching line groove cutting function, and one machine can be used for two purposes
- » Equipped with automatic splitting equipment, easy to operate with high efficiency

Application field

Widely used in scribing of GPP wafers.



Technical Parameter

Model	TH-4212
Laser source	IR
Wavelength	1064nm
Laser power	20W/30W
Max. Wafer dimension	4 inch
Scribing speed	150mm/s、200mm/s
Line width	40~50μm
Line depth	50-120μm
Positioning accuracy	5μm
Repositioning accuracy	2μm
Laser service life	100,000 hours
Dimension	1280x900x1620mm
Total weight	700kg

Full Automatic Wafer Laser Cutting Machine

Features

- » Automatic loading and unloading, automatic alignment and scribing speed, high efficiency, reduce fragmentation rate
- » Non-contact processing without mechanical stress, thus improving wafer quality
- » CCD quick positioning function
- » High accuracy 2D linear motion platform and high accuracy DD rotation platform
- » Marble base with high stability and low thermal deformation
- » CNC control
- » Friendly interface and easy to operate
- » Scribing technology expert system
- » High reliability and stability
- » Upgradable double-sided CCD recognition function
- » Wafer backside scribing cross alignment function
- » Equipped with automatic splitting equipment, easy to operate with high efficiency

Application field

Widely used for scribing and cutting of IC wafer, GPP wafer and Low-K engraving.



Technical Parameter

Model	TH-6212
Laser source	IR
Wavelength	1064nm
Laser power	20w/30w
Max. Wafer dimension	5 inch (6inch compatible)
Scribing speed	150mm/s、200mm/s
Line width	35~45μm
Line depth	< 120μm (depending on material)
Positioning accuracy	±5μm
Repositioning accuracy	±2μm
Laser service life	100,000 hours
Dimension	960*730*1740mm
Total weight	660kg

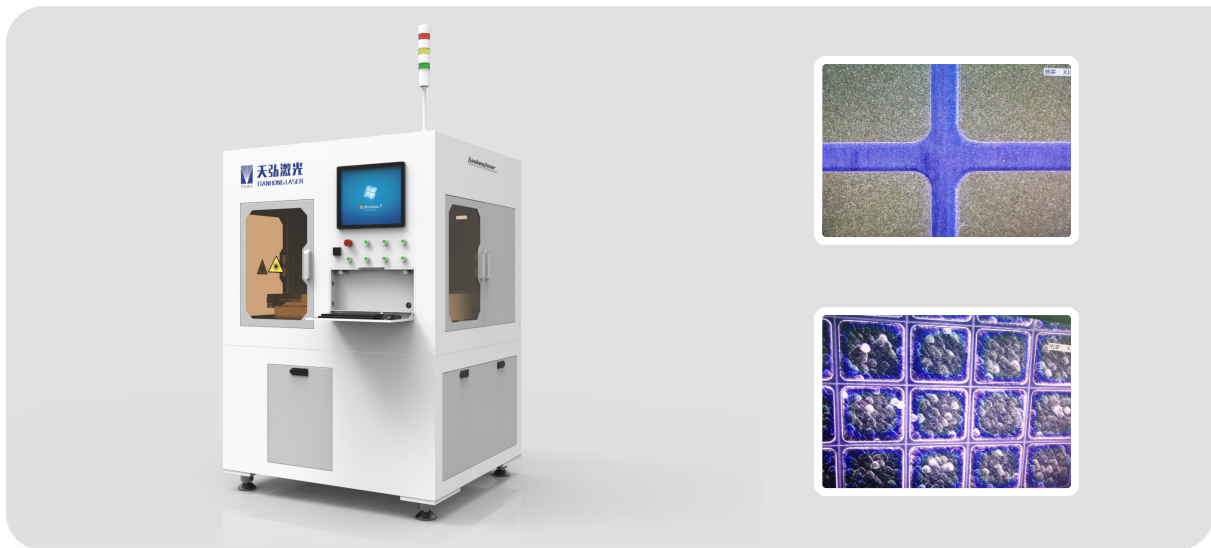
Full Automatic Wafer Laser Cutting Machine

Features

- » Automatic loading and unloading, automatic alignment and scribing speed, high efficiency, reduce fragmentation rate
- » Non-contact processing without mechanical stress, thus improving wafer quality
- » CCD quick positioning function
- » High accuracy 2D linear motion platform and high accuracy DD rotation platform
- » Marble base with high stability and low thermal deformation
- » CNC control
- » Friendly interface and easy to operate
- » Scribing technology expert system
- » High reliability and stability
- » Upgradable double-sided CCD recognition function
- » Wafer backside scribing cross alignment function
- » Equipped with automatic splitting equipment, easy to operate with high efficiency

Application field

Widely used for scribing and cutting of IC wafer, GPP wafer and Low-K engraving.



Technical Parameter

Model	TH-8211	TH-8212
Laser source	UV	UV
Wavelength	355nm	355nm
Laser power	10w/15w/30w	10w/15w/30w
Max. Wafer dimension	5 inch (6inch compatible)	5 inch (6inch compatible)
Scribing speed	1000/1500/3000mm/s	50/80/100mm/s
Line width	150-300μm	20-40μm
Line depth	< 10μm (depending on material)	< 120μm (depending on material)
Positioning accuracy	±5μm	±5μm
Repositioning accuracy	±2μm	±2μm
Laser service life	12,000 hours	12,000 hours
Dimension	1260*1160*1820mm	1260*1160*1820mm
Total weight	1500kg	1500kg

Wafer Laser Marking Machine

Features

- » This equipment is mainly aimed at the etching of graphics and logos in semiconductor wafers, and uses the corresponding precise positioning and identification system to realize automatic identification of processed parts.
- » Using a multi-axis robot or a handling module to realize the automatic unloading function and complete automatic processing.

Application field

Widely used for wafer graphics and wafer logos etching processing.



Technical Parameter

Model	TH-JYA-FLMS20	TH-JYB-FLMS20	TH-JYB-FLMS3	TH-JYB-FLMS5
Laser source	IR		UV	
Wavelength	1064nm		355nm	
Laser power	20W/30W		3W/5W	
Standard position accuracy	±0.1mm			
Reclaimer	Six-axis manipulator		Multi-axis servo module	
Positioning method	CCD Contour Positioning CCD			
Dimension	1200x1600x2000mm		1280x850x1700mm	
Laser service life	100,000 hours		15,000 hours	

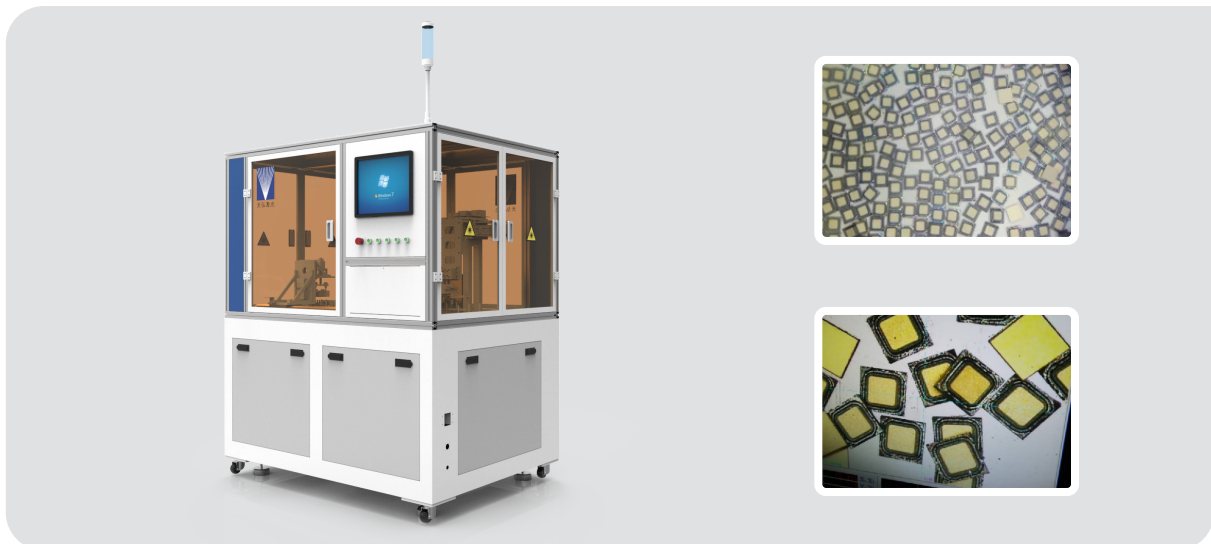
Automatic Wafer Edge Stripping Machine

Features

- » This equipment is a high-end automatic splitting equipment mainly developed for GPP wafers; it is equipped with automatic loading and unloading, Z-axis pressure sensing, visual angle correction, double-wafer detection, and automatic liquid spraying functions;
- » The equipment has high mechanical yield and fast splitting efficiency;
- » Friendly interface and easy to operate
- » Process parameters can be stored and retrieved, easy to operate;
- » Pressure value sensing, can be displayed as a graph;
- » Automatic drainage system.

Application field

Widely used in the edge stripping of integrated circuit wafers and GPP wafers.



Technical Parameter

Model	TH-LP-05
Stick diameter	10-30mm can be customized
Stick material	Stainless steel
Receiving method	Belt conveyor / stack collection
Max. Wafer dimension	5 inch
Max. Wafer thickness	400um (depending on the material)
Wafer Alignment	CCD image capture target, automatic angle correction
Wafer alignment accuracy	±0.5°
Repetition pressure accuracy	±5N
Dimension	1500*1204*2415mm
Total weight	600kg

New energy industry series equipment

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Film Solar Cell Edge Laser Cleaning Machine

Features

- » The device can move the platform longitudinally and the optical box horizontally according to the need, so that the laser head can be scanned quickly under the designated area of the battery chip, and the film layer of the designated area of the battery chip can be removed by the vibrating mirror.
- » High degree of automation (optional automatic loading and unloading), high efficiency of the whole machine (processing efficiency increased by 300).
- » Laser scanning can only remove the film, and it cannot damage the film.
- » The film that has not been removed by laser is not damaged and polluted by dust.
- » After the workpiece edged by laser through the insulation performance test, insulation resistance value >1000M after lamination.
- » Dust removal effect: after edge cleaning, 400 times microscope is used to check the clear edge area without more than 1 micron pellet.

Application field

Suitable for film cell industry.



Technical Parameter

Model	TH-5212
Wavelength	1064nm
Laser pulse width (typical)	70ns, 10kHz, 1064nm
Laser pulse stability	<3%(RMS) up to 15KHz
Output method	Single machine single laser single optical path output
Z-axis spot focal plane adjustment	Floating trimming
Average processing speed	200-400 mm/s
Average edge clearing efficiency	≤ 1 minute / board (edge clearing width ≤ 15mm)
Motion straightness	±10μm/m
Workbench flatness	50μm
Edge clearing accuracy	±0.1mm
Spot diameter	0.5-1mm
Spot shape	Square spot
Effective processing range	635mm X400mm (can be customized)
Resistance value	1000MΩ, 1000VDC
Chiller water supply	Deionized water

Film Solar Cell Laser Processing Equipment

Features

- » In order to obtain high efficiency amorphous / microcrystalline silicon laminated thin film solar cell, laser cutting is one of the key technologies to achieve the good performance of the components. The equipment of microcrystalline silicon thin film solar cells after the introduction of the P2, P3 (second and third) laser marking processing for high efficiency amorphous silicon / gain laminated microcrystalline silicon thin film solar cell module provides a good data base.
- » When the scribing process is performed, the substrate glass faces upward, and the coating surface faces downwards, and the laser marks the film surface through the glass.
- » The dust generated in the laser scribing process is sucked away from the lower side through the dust collector in real time.
- » Adopts CCD imaging system

Application field

Processing film: copper、indium、gallium、selenium、cadmium telluride、perovskite.



Technical Parameter

Model	TH-LPE-G-6000
Laser	532nm+1064nm
Processing format	450mmX450mm(can be customized)
Focus spot	≤ 0.02mm
Etching line width	<40um
Workbench positioning accuracy	±2um
Workbench repetition accuracy	±1um

Display industry series devices

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Film Cutting Machine

Features

- » Adopts sealed-off CO2 metal-encapsulated RF laser, which has a working life of more than 450,000 hours, and can be used for recycled circulation .
- » The maximum curve movement speed: 50000 mm/min, which is an artifact of both high speed and high stability.
- » The equipment optimizes the cutting path, supports the automatic overcut function of closed graphics, and ensures that the cutting seam is smooth and flat.
- » Standard configuration, including auto focus, red light preview, blowing auxiliary device, easy operation and more user-friendly characteristic.
- » The laser power and the engraving and cutting speed can be freely controlled, and the laser energy control: 0-100% can be set by the software.

Application field

Applicable to the mobile phone film industry, communications, consumer electronics, PMMA, packaging and printing, clothing, leather, computer embroidery cutting, models, templates, handicrafts, advertising decoration, paper products and other industries.



Technical Parameter

Model	32 inch-43 inch	43 inch-110 inch
Processing format	600mmx700mm (can be customized)	2500mmx1600mm (can be customized)
Laser power	30w/60w/100w	
Wavelength	9.3um/10.6um	
Positioning method	CCD	
Driven method	Servo motor + screw	Servo motor + rack and gear
Positioning accuracy	±0.05mm	±0.05mm
Repetition accuracy	±0.01mm	
Max. speed	≤ 60m/min	
Processing line width	0.1mm±0.02mm	
Electricity demand	Three-phase 380V/50HZ/3.5KW	
Dimension	1700x1600x1500mm	3760x2590x1340mm
Weight	900kg	3250kg

CO₂ Laser Die Cutting Machine

Features

- » Imported laser source, with good cutting effect and long service life.
- » Imported galvo with fine cutting line, high speed and stability.
- » Equipped with ventilation system. Install the smoke pipe near the cutting point to extract the smoke generated during cutting.
- » Equipped with adsorption platform, which ensures plane cutting. Ensure that the PET film is flat and has no displacement during cutting and moving.
- » Easy to operate and environment protection.

Application field

Mobile shell side laser carving/engraving. Logo cutting of mobile, computer, etc.



Technical Parameter

Model	TH-MQ-CO2LMS150
Max. laser power	150w
Max. consumption	5KW
Engraving line speed	≤ 12000mm/s
Min. Line width	0.1mm
Min. character	0.5mm
Engraving range	80mmx80mm/100mmx100mm (optional)
Platform movement range	400x400mm (can be customized)
Platform movement speed	≤ 300mm/s
CCD positioning accuracy	±0.01mm
Platform repetition accuracy	±0.02mm
Electricity demand	220V/ single phase 50HZ/20A
Controlling method	Motion control card, Tianhong specialized die-cutting software
Cutting method	CO ₂ laser, galvanometer processing + XY platform processing
Positioning method	CCD positioning, 2D servo mobile platform
Automation degree	Manual loading, automatic engraving and cutting, manual reclaiming
整机外形尺寸	1040x1732x1672mm

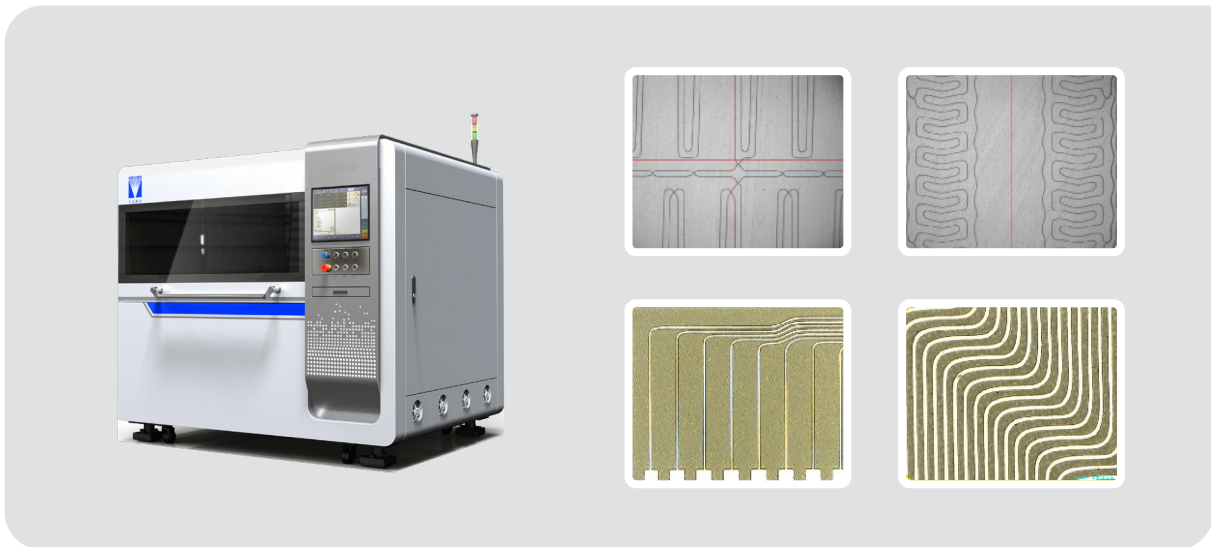
ITO Laser Etching Machine

Features

- » The marble platform is driven by a linear motor to ensure the precision and stability of the high-speed operation of the equipment.
- » The multi-waveform adjustable pulse width version of the imported SPI laser ensures the consistency of the processing effect of different products.
- » The processing table can be customized, and the functions of double-head and multi-head equipment can also be customized.
- » Original German imported galvanometer to ensure processing accuracy and splicing effect.

Application field

Capacitive screen wire and visible area etching in capacitive touch panel, high-speed direct etching of silver paste, ITO, graphene, nanosilver, carbon nanotube, polymer conductive film and other materials on PET/ PC / PMMA / and glass substrates.



Technical Parameter

Model	TH-TPL2514-1	TH-TPL2514-2
Laser	MOPA	
Working head	1	2
Laser working mode	Pulse	
Wavelength	1064nm	
Laser power	20W	
Etching line width and line spacing	25μm~45μm (depending on processing material)	
Single field lens processing format	170X170mm/120X120mm	
Working platform	500X500mm/800X800mm (can be customized)	
Effective processing area	Can be transferred, width: 1400mm, length (customized on demand)	
Scanning accuracy	±5μm(f=25φ170)	
Comprehensive positioning accuracy	±10μm	
Repositioning accuracy	±2μm	
Stitching accuracy	≤ 10um (splicing point can be set according to customer needs)	
Motion platform	Linear motor	
Machining workpiece	Silver paste, ITO, nanosilver, graphene, etc. on PET substrate	
Electricity demand	Three-phase 380V/50HZ/5KW	
Dimension	1770X1420X1810mm	

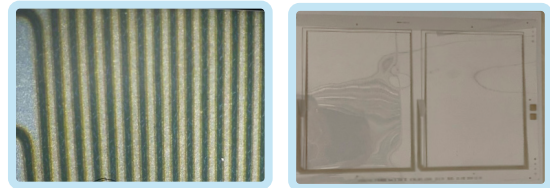
Multi-head ITO Laser Etching Machine

Features

- » Using high-precision laser processing direct writing scanning technology, which is applied to various graphic direct writing and etching processing in resistive and capacitive touch panels.
- » With the array pattern of X-axis and Y-axis linear motor platform, it can simultaneously realize high-speed direct writing and etching processing of “Ag, ITO, nano-silver, graphene” which are applied to Glass or PET coil substrates. The equipment has high stability and high performance, high security, tenfold increase in production efficiency.
- » The equipment supports automatic loading and receiving system, which can realize full automatic processing. The equipment has optimized the adsorption platform and dust collection function for large-size products. It adopts a full marble table, bilateral drives, and supports high-speed target grabbing.

Application field

In the capacitive touch panel, applied in the etching of capacitive screen wire and visible area, and the high-speed direct writing and etching of materials such as silver paste, ITO, graphene, nano-silver, carbon nano-tube, polymer conductive film, etc. on PET/ PC / PMMA / and glass substrates.



Technical Parameter

Model	TH-LD-AGE2	TH-LD-AGE8	TH-LD-AGE10
Laser	MOPA		
Working head	2	8	10
Wavelength	1064nm		
Laser power	20W		
Etching line width and line spacing	30μm~45μm (depending on processing material)		
Single field lens processing format	170X170mm		
Working platform	86 inch	100 inch	100 inch
Effective processing area	Can be transferred, width: 1400mm, length (customized on demand)		
Comprehensive positioning accuracy	±5μm		
Repositioning accuracy	±2μm		
Stitching accuracy	≤ 10um (splicing point can be set according to customer needs)		
Motion platform	Linear motor		
Processing positioning method	Automatically use CCD positioning system for automatic positioning and pattern adjustment processing		
Smoke-exhausting method	Independently design the smoke-exhausting system collection pipe to ensure a safe production environment		
Machining material	Silver paste, ITO, nanosilver, graphene, etc. on PET substrate		
Electricity demand	Three-phase 380V 50HZ 5kw		
Total weight	About 4000Kg	About 4000Kg	About 4500Kg

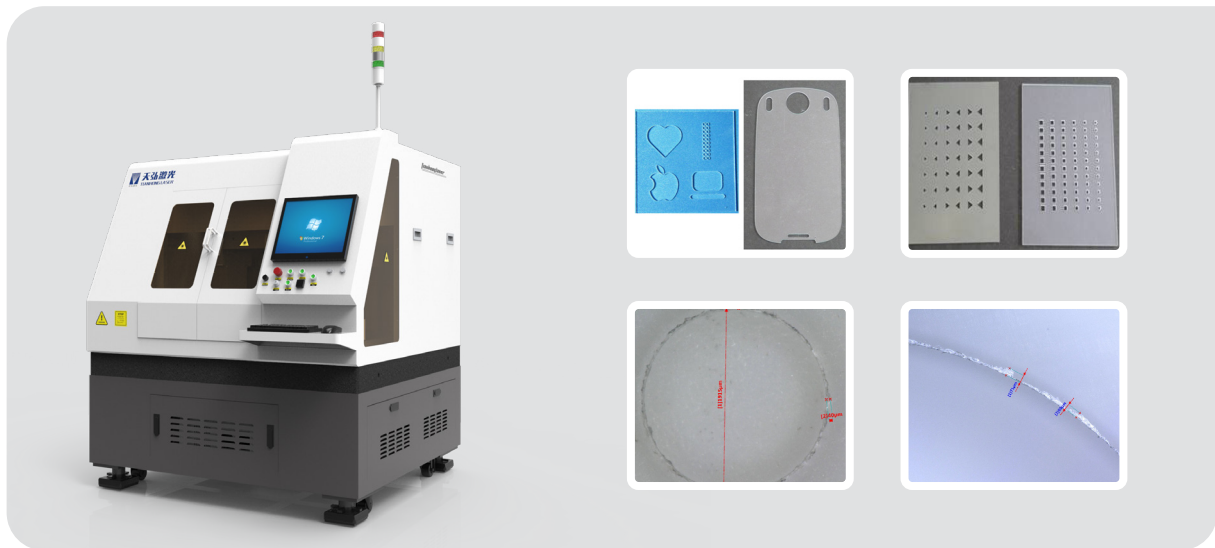
Glass Laser Drilling Machine

Features

- » Compact structure, small occupying space, easy to use. Originally from China, smaller and more flexible.
- » Basic configuration, using imported lasers from Europe and the United States, with 3D dynamic focusing galvanometer scanning system, the processing speed can reach 40 mm/s, cutting edge chipping $\leq 70\mu\text{m}$. Sub-picosecond laser cutting edge chipping $\leq 40\mu\text{m}$, processing size: 0.1mm-90 mm.
- » Intelligent CCD vision system, realizes automatic sluggish recognition, precise positioning and calibration, and CCD can be used for visual inspection.
- » Directly edit or import cutting programs, automatic counting function, set the number of cuttings at will and count the total number of cut products.

Application field

Suitable for drilling and cutting of various glass in optoelectronics, flat display, mobile phone, semiconductor, medical, home appliances, solar energy, construction, automobile and other industries.



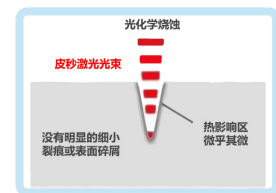
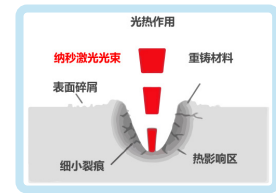
Technical Parameter

Model	TH-G-LD-30
Cutting path	500×500 (mm)
Processing positioning method	CCD positioning
Wavelength	532nm
Laser power	10w 12w 20w 30w optional
Repetition accuracy	0.005mm
Positioning accuracy	$\pm 0.01\text{mm}$
Machining chipping	$\leq 70\mu\text{m}$
Minimum hole diameter	0.1mm
Single field lens cutting format	50mm×50mm
Glass thickness range	$\leq 6\text{mm}$
Electricity demand	Three-phase 380V/60Hz
Dimension	1540x1460x1752mm
Total weight	2300kg

Infrared Picosecond Glass Laser Drilling Machine

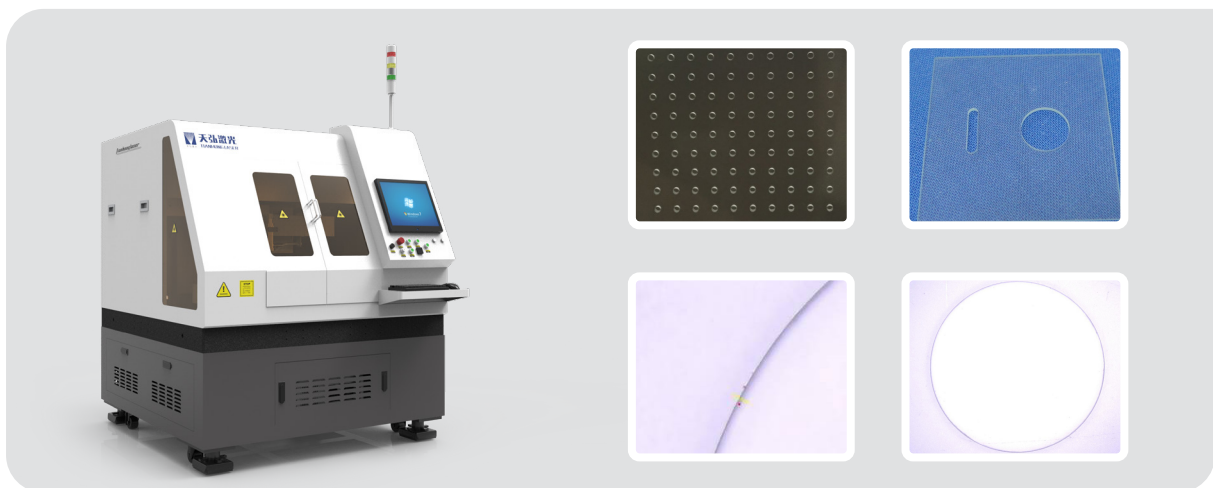
Features

- » The laser adopts picosecond laser, which has small cutting edge chipping, high strength after cutting, and small heat affected area.
- » The optical path system adopts imported lenses to ensure high-quality optical transmission.
- » The machine is all made of marble stone, which has good flatness, is not easy to deform, and has strong shock absorption and shock absorption ability, ensuring the stability of equipment processing.
- » The equipment adopts imported high-speed galvanometer, which has high processing precision and good long-term stability.



Application field

Widely used in smart phone glass cutting, tablet computer glass cutting, LCD TV glass panel cutting and other industries.



Technical Parameter

Model	TH-G-LD-ps-20
Cutting path	500×500 (mm)
Processing positioning method	CCD positioning
Wavelength	1064nm
Laser power	10w 20w 30w optional
Repetition accuracy	0.005mm
Positioning accuracy	±0.01mm
Machining chipping	≤ 20um
Minimum hole diameter	0.1mm
Single field lens cutting format	50mm×50mm
Glass thickness range	≤ 1mm
Electricity demand	Three-phase 380V/60Hz
Dimension	1540x1460x1752mm
Total weight	2300kg

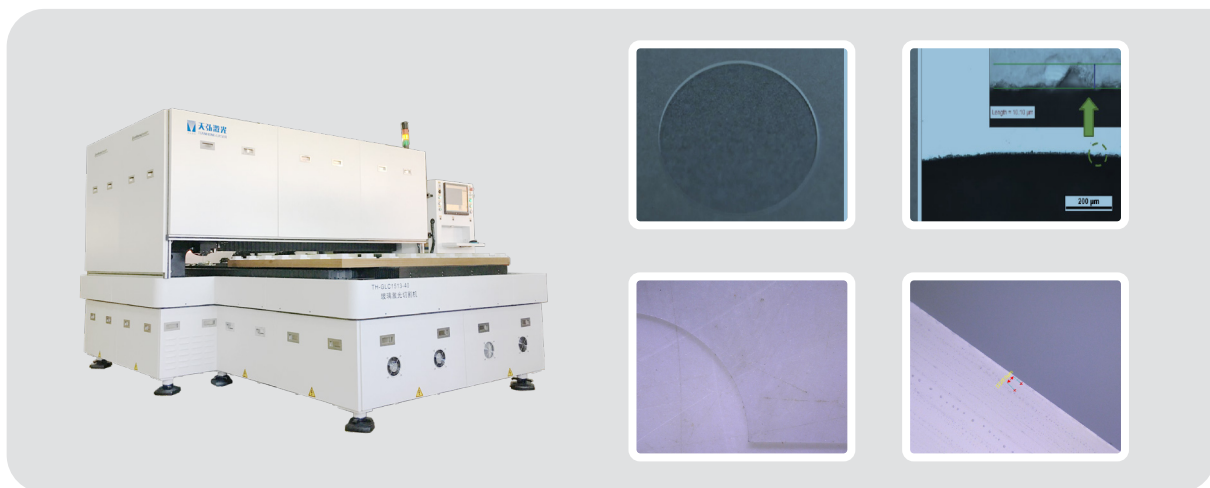
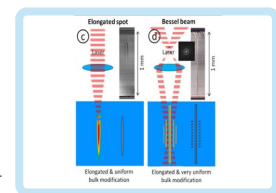
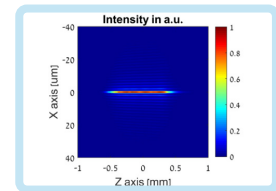
Infrared Picosecond Laser Wire Cutting Machine

Features

- » The equipment adopts marble platform. X/Y system adopts linear motor drive system to ensure the accuracy and stability of the platform while running at high speed.
- » Equipped with high-pixel CCD automatic alignment function to ensure product cutting alignment accuracy.
- » Imported high-power picosecond laser, PSO signal control mode, to ensure that the laser spot spacing is uniform when the platform accelerates and decelerates.
- » Adopt imported optical gas elements, with reliable quality.

Application field

This equipment is suitable for straight or special-shaped cutting of ordinary glass or chemically strengthened glass. Mainly used in mobile phone glass cover, ultra-narrow frame LCD, OLED, LTPS and other display panel glass, as well as glass slides in the medical industry and glass cutting in architectural glass, automotive glass and other industries.



Technical Parameter

Model	TH-G-LD-ps-20
Cutting path	500×500mm (can be customized)
Laser pulse width	<15ps
Wavelength	1064nm
Laser power	40w optional
Repetition accuracy	2um
Comprehensive positioning accuracy	±5um
Max. speed	≤ 1000mm/s
Minimum machining radius	≥ 1mm
Glass material	Ordinary glass or chemically strengthened glass (DOL<60um)
Machining chipping	≤ 10um
Electricity demand	Three-phase 380V/60Hz
Dimension	1200x1400x1600mm
Total weight	2300kg

Filter Laser Cutting Equipment

Features

- » The cutting edge is smaller than the cutter wheel, less than 20 μ m.
- » Cutting without water consumption and blade to achieve low consumption cutting.
- » The cutting efficiency is 6-8 times that of the cutter wheel.
- » The cutting cost is much lower than the cutter wheel.
- » Able to cut large warped films, both AR and IR surfaces can be cut.
- » Fully automatic cutting, less dependence on manpower, to ensure the stability of cutting effect.

Application field

Suitable for the cutting of coated glass (filters) in the camera industry.

Used for linear processing of thin glass or transparent materials in electronics, medical, display and other industries.



Technical Parameter

Model	TH-G-ps-5
Cutting path	500×500mm (can be customized)
Laser pulse width	<15ps
Wavelength	532nm
Laser power	5w
Repetition accuracy	±1 μ m
Comprehensive positioning accuracy	±2 μ m
Max. speed	≤ 800mm/s
Max. processing glass thickness	≤ 1mm
Glass material	Filter or ordinary white glass
Machining chipping	≤ 20 μ m
Electricity demand	Three-phase 380V/60Hz
Dimension	1200x1400x1600mm
Total weight	2300kg

FPC/PCB series equipment

BETTER TIANHONG BETTER LASER

UV Laser Cutting Machine

Features

- » Smooth cutting edge without burrs, dust and kernel.
- » High accuracy exterior cutting, especially suitable for cutting of small arc.
- » One step cutting for complex materials with different thickness.
- » Non-contact machining without thermal deformation.
- » Linear motor driven of platform with high speed and steady feeding.
- » Imported power measuring system. It can detect laser power at arbitrary time to ensure quality.
- » Low thermal effect on workpiece without laminate. Low defective rate.
- » Positioning holes are preserved on platform, which makes it easy to fix PCB and processing. Vacuum absorb platform without any fixtures.
- » One time machining of different shape, decrease delivery period.
- » Imported image positioning technology for high accuracy machining.

Application field

Flexible circuit board cutting/ ultra-thin metal cutting, cover film cutting; Laser drilling, LTCC drilling, etc. Patch PCB molding. COB cutting; GBA/Connecting Fingers repair/Permeability gold eliminate/Repair welding plate. SD card cutting.



Technical Parameter

Model	TH-UV500A	TH-UV**A
Laser source	UV	
Laser power	8w~20w optional	
Wavelength	355nm	
Galvanometer single processing range	50x50mm (Telecentric Lens)	
Processing positioning method	Automatically use CCD positioning system for automatic positioning and pattern adjustment processing	
Comprehensive positioning accuracy	±10um	
Repetition accuracy	±2um	
Linear motor platform path	500x500mm	500x500mm
Processing platform format	480mmx350mm	480mmx350mm
Electricity demand	Three-phase 380V/50HZ/3.5KW	
Air pressure	0.5-0.8MPa	
Environmental requirements	20° C ± 3° C	
Dimension	2060x1860x1590mm	
Total weight	2500kg	

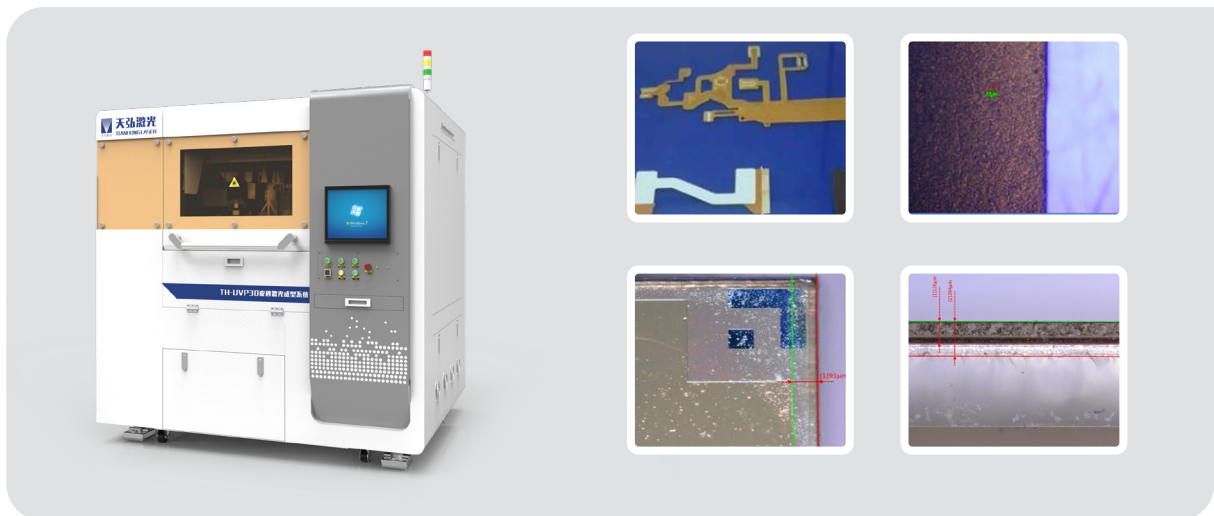
Picosecond UV Laser Cutting Machine

Features

- » The equipment adopts ultra-short pulse ultraviolet picosecond laser, which has the advantages of high processing efficiency, small heat-affected zone, no need for subsequent auxiliary processing, etc., and can achieve “cold” processing technology.
- » The equipment adopts the marble platform. X/Y system adopts the linear motor drive system to ensure the accuracy and stability of the platform’s high-speed operation.
- » Equipped with high-pixel CCD automatic alignment function to ensure product cutting alignment accuracy.
- » Equipped with high-precision galvanometers to ensure product processing accuracy and corner process effects. The repetition accuracy can reach 1.5um.

Application field

Used in the mobile phone industry, communications, consumer electronics, semiconductors, scientific research, biomedical and other fields. For example, laser precision cutting, drilling and etching of non-metallic composite materials such as flexible OLED screen, LCP, PI film, FPC, nano-gold, polarizer, and FPC cover film.



Technical Parameter

Model	TH-500C	TH-UV500B
Laser source	UV	
Laser power	8w~20w optional	
Wavelength	355nm	
Galvanometer single processing range	50x50mm (Telecentric Lens)	
Processing positioning method	Automatically use CCD positioning system for automatic positioning and pattern adjustment processing	
Comprehensive positioning accuracy	±10um	
Repetition accuracy	±2um	
Linear motor platform path	500x500mm	420x420mm
Processing platform format	480mmx350mm	480mmx350mm
Electricity demand	Three-phase 380V/50HZ/3.5KW	
Air pressure	0.5-0.8MPa	
Environmental requirements	20° C ± 3° C	
Dimension	2060x1860x1590mm	1040x1280x1700mm
Total weight	2500kg	750kg

Marking industry series equipment

BETTER TIANHONG BETTER LASER

Fiber Laser Marking Machine

Features

- » Equipped with IPG, SPI, Raycus laser source with 100,000 hours working time on average. With reflection and isolation protection function and high peak power.
- » Compact design, suitable for continuous assembly line work. High working frequency, thus increasing the marking speed effectively.
- » PC controlled, friendly interface and easy operation. Adopt general software to input pattern documents, easy input and powerful.
- » Single mode output. Superior beam quality.

Application field

Widely applied in the marking of plastic button and electronic components, chips, coding of paper and food package. Especially suitable for high precision and fine marking, such as watches, mold industry and bitmap marking. Also applies to remove the oxide layer of aluminum-magnesium alloy.



Technical Parameter

Model	TH-FLMS20	TH-FLMS30	TH-FLMS50	TH-FLMS100	TH-FLMS200	TH-FLMSMP20	TH-FLMSMP30	TH-FLMSMP60
Wavelength	1064nm							
Laser source	Fiber laser					MOPA laser		
Laser power	20w	30w	50w	100w	200w	20w	30w	50w
Cooling way	Air cooling							
Marking range	100x100mm optional							
Repetition accuracy	±0.003mm							
Min. Line width	0.045mm							
Single point energy	1.5mj							
Beam quality	≤ 1.2					≤ 1.3		≤ 1.5
Pulse width	100ns					2-350ns		
Pulse repetition frequency	20-200kHz					1-4000KHZ		
Engraving speed	≤ 7000mm/s							
Protection class	IP54							

UV Laser Marking Machine

Features

- » UV laser marker is equipped with diode end-pump as laser source. It boasts high conversion rate between laser and electricity. Output wavelength is 355nm. Laser power can be selected. Specialized in marking and precision drilling of special materials in industrial processing.
- » Adopt advanced hardware control technology and intelligent software; low energy consumption and easy to maintain; high precision marking quality and stability.
- » PC controlled, friendly interface and easy operation; Adopt general software to input pattern documents, easy input and powerful.
- » Ultra-thin light spot matches electronic precision machining.

Application field

Suitable for marking on glass surface, polymer material and tiny hole processing. Widely applicable to marking on packing materials of food, drilling tiny hole (hole diameter < 10um). Flexible PCB,LCD,TFT marking and slicing. Thin film removal of metallic and non-metallic materials.Silicon wafer tiny hole and blind hole processing.



Technical Parameter

Model	TH-UVLMS3	TH-UVLMS5	TH-UVLMS8	TH-UVLMS10	TH-UVLMS15
Wavelength	355nm				
Laser power	3w@50KHz	5w@50KHz	8w@50KHz	10w@50KHz	15w@50KHz
Engraving range	100 X 100mm (optional)				
Min. character	0.15mm				
Engraving speed	≤ 7000mm/s				
Repetition accuracy	±0.003mm				
Min. line width	0.01mm (Depending on material) @ F=160 mm				
Beam quality	≤ 1.3				
Pulse repetition frequency	30-150kHz	100 uj	267 uj	250 uj	> 300 uj
Power consumption	1000w	1000w	2500w	3000w	3000w
Cooling way	Air cooling/water cooling	Air cooling/water cooling	Water cooling	Water cooling	Water cooling

CO₂ Laser Marking Machine

Features

- » Adopt far-infrared ray laser. Adopt imported CO₂ RF laser or domestic laser with better laser mode, longer working life and higher reliability. Suitable for long time industrial working.
- » CO₂ laser source with low price and easy maintenance.
- » PC controlled, friendly interface and easy operation. Adopt general software to input pattern documents, easy input and powerful.
- » Key components are sourced from America and Germany.
- » High speed galvo scanning system, suitable for mass production.

Application field

It's suitable for marking or engraving on nonmetallic materials, such as PMMA (arylic), organic glass, bamboo and wood, resin,plastics, rubber,paper,cloth,leather, home appliance, IC, etc.



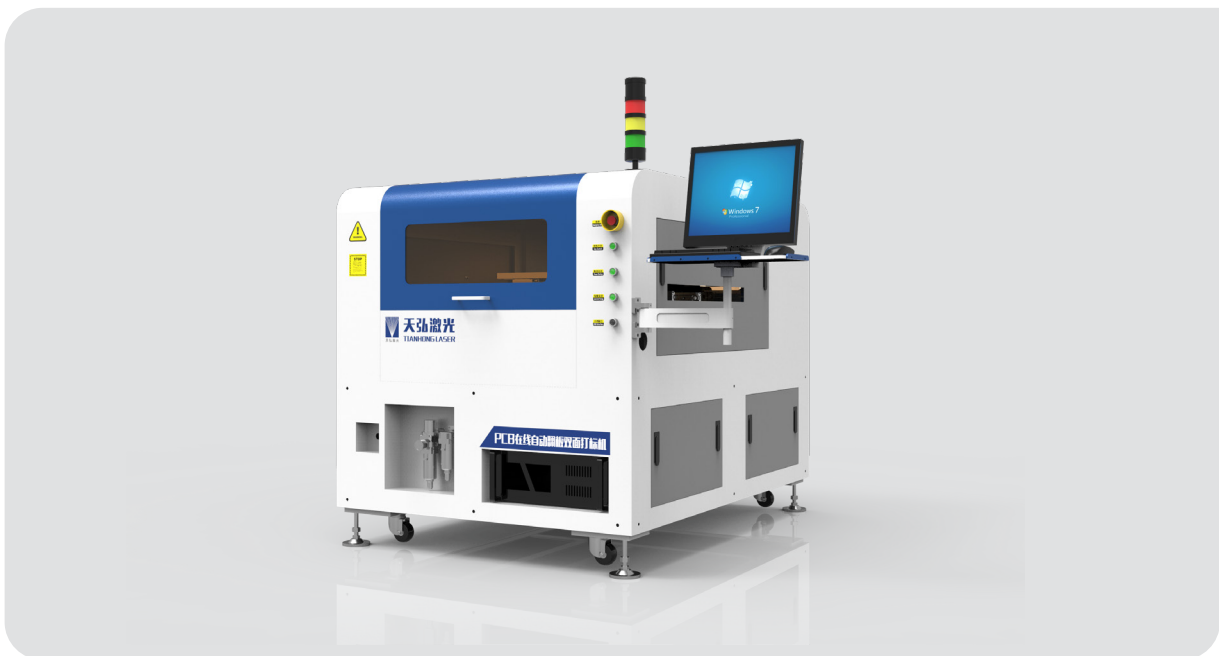
Technical Parameter

Model	TH-CO2LMS10	TH-CO2LMS30	TH-CO2LMS50	TH-CO2LMS60	TH-CO2LMS100
Wavelength	10.6um				
Laser power	10w	30w	55w	60w	100w
Engraving range	100x100mm (optional)				
Engraving line speed	≤ 7000mm/s				
Min. line width	0.1mm (depending on material)				
Min. character	0.5mm (depending on material)				
Repetition accuracy	±0.005mm				
Protection class	IP54				
Cooling way	Air cooling			Water cooling	
Voltage	Two-phase AC 220V				
Best use environment	Temperature: 15°C -30°C Humidity: 45%-75%				

PCB Automatic Double Sided Laser Marking System

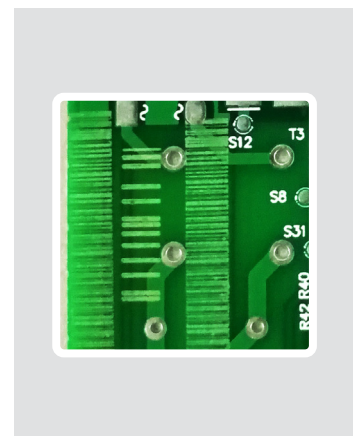
Features

- » High intelligence, high production efficiency, high precision, strong system stability, automatic scanning and error alarm function, high protection level, fully meet the requirements of environmental protection.
- » High speed digital mirror, high performance CO2 laser, fast speed, precision accuracy, stable performance, can work for 24 hours in a continuous period.
- » With PLC controller, I/O signal transmission can be carried out with the customer's machine.
- » Support MES system.



CO2 PCB MARKING SYSTEM

Model	TH-PCB-M10
Laser source	CO ₂
Max. laser power	10W
Marking speed	≤ 7000mm/s
Repetition marking accuracy	±0.01mm
Max. Engraving range	100mm*100mm (field lens optional)
Min. Line width	0.1mm
Applicable PCB Specifications	Min: 50mm*50mm, Max: 510mm*460mm
Applicable PCB Thickness	0.8mm-5mm
PCB weight	≤ 0.4kg
QR code engraving range	1.5mm*1.5mm-10mm*10mm
QR code engraving characters	1.5*1.5mm/15; 2*2mm/25; 3*3mm/50; 5*5mm/100
Yield	100%
X/Y axis movement speed	300mm/s



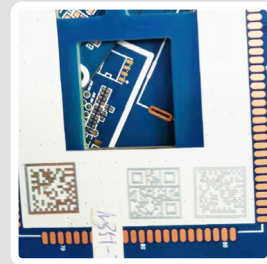
FIBER OPTIC PCB MARKING SYSTEM

Model	TH-PCB-M20	TH-PCB-M30
Laser source	FIBER	
Max. laser power	20W	30W
Marking speed	≤ 7000mm/s	
Repetition marking accuracy	±0.01mm	
Max. Engraving range	100mm*100mm (field lens optional)	
Min. Line width	0.1mm	
Applicable PCB Specifications	Min: 50mm*50mm, Max: 510mm*460mm	
Applicable PCB Thickness	0.8mm-5mm	
PCB weight	≤ 0.4kg	
QR code engraving range	1.5mm*1.5mm-10mm*10mm	
QR code engraving characters	1.5*1.5mm/15; 2*2mm/25; 3*3mm/50; 5*5mm/100	
Yield	100%	
X/Y axis movement speed	300mm/s	



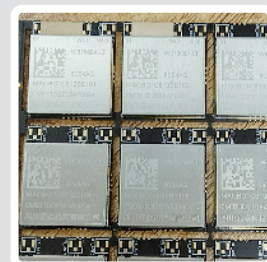
UV PCB MARKING SYSTEM

Model	TH-PCB-M3	TH-PCB-M5
Laser source	UV	
Max. laser power	3W	5W
Marking speed	≤ 7000mm/s	
Repetition marking accuracy	±0.01mm	
Max. Engraving range	100mm*100mm (field lens optional)	
Min. Line width	0.1mm	
Applicable PCB Specifications	Min: 50mm*50mm, Max: 510mm*460mm	
Applicable PCB Thickness	0.8mm-5mm	
PCB weight	≤ 0.4kg	
QR code engraving range	1.5mm*1.5mm-10mm*10mm	
QR code engraving characters	1.5*1.5mm/15; 2*2mm/25; 3*3mm/50; 5*5mm/100	
Yield	100%	
X/Y axis movement speed	300mm/s	



GREEN PCB MARKING SYSTEM

Model	TH-PCB-M6
Laser source	GREEN LIGHT
Max. laser power	6W
Marking speed	≤ 7000mm/s
Repetition marking accuracy	±0.01mm
Max. Engraving range	100mm*100mm (field lens optional)
Min. Line width	0.1mm
Applicable PCB Specifications	Min: 50mm*50mm, Max: 510mm*460mm
Applicable PCB Thickness	0.8mm-5mm
PCB weight	≤ 0.4kg
QR code engraving range	1.5mm*1.5mm-10mm*10mm
QR code engraving characters	1.5*1.5mm/15; 2*2mm/25; 3*3mm/50; 5*5mm/100
Yield	100%
X/Y axis movement speed	300mm/s



Fly Laser Marking Machine

Features

- » The equipment adopts imported maintenance-free CO2 gas laser, fiber laser, ultraviolet laser, and is equipped with a special galvanometer which is suitable for laser coding of various packaging and production lines.
- » By using different lasers to realize the coding and marking of different materials, instead of ink coding of the date, batch number and text on various products.
- » Compared with it, it has the advantages of durability, high anti-counterfeiting, no pollution, no consumables, low cost, simple and convenient operation, etc. It is suitable for mass production.
- » PC controlled, friendly interface and easy operation; Adopt general software to input pattern documents, easy input and powerful.

Application field

Suitable for marking of various non-metallic materials such as paper, glass, plastic, leather, wood, etc. It is especially suitable for industries such as food and beverage, cosmetics, medicine, cigarettes, electronic components and other large-scale assembly line production.



Technical Parameter

Model	TH-CO2LMS30	TH-CO2LMS60	TH-UVLMS50W	TH-UVLMS100W	TH-FLMS50W	TH-FLMS51W
Laser source	Imported CO2 laser		UV		Fiber	
Laser power	30w/50w/60w/100w					
Marking method	Vector / Lattice (5x7/6x12/7x14/8x16/12x24) method					
Marking range	50x50mm, 75x75mm, 110x110mm (optional)					
Focus depth	Varies with the size of the field lens					
Information output method	Text String Mode					
Text	Any line within the marking range (adjustable)					
Flying marking speed	Steady state value ≤ 130m/min					
Character height	Adjustable (unit: mm)					
Font	Support SHX single-line fonts and have the company's customized laser marking fonts					
Marking options	Fully automatic serial number, batch number and real-time clock, automatic production date					

Nameplate Automatic Laser Marking Machine

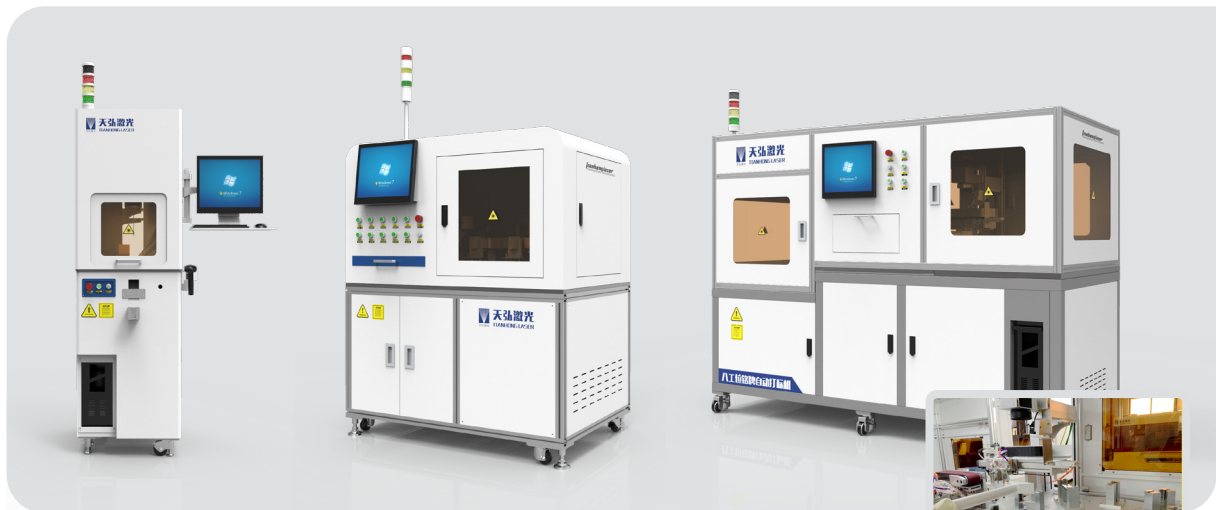
Features

- » High durability, high anti-counterfeiting, no pollution, no consumables, low cost, simple and convenient operation, etc. Suitable for mass production.
- » PC controlled, friendly interface and easy operation; Adopt general software to input pattern documents, easy input and powerful.
- » IPG, SPI, Raycus and other brands of fiber lasers are used, with reflection isolation protection function, high output peak power, and an average trouble-free working time of 100,000 hours.
- » Single-mode output, precise spot.



Application field

The equipment is aimed at marking metal nameplates, with compact structure, high reliability, powerful software functions, flexible operation, and close to the production itself. Professionally used in batch and streamlined nameplate marking.



Technical Parameter

Model	TH-MP-FLMS-20	TH-MP-FLMS-50	TH-MP-FLMS-100
Laser source	Imported IPG fiber laser		
Wavelength	1064nm		
Positioning method	Fixture shape positioning	Fixture shape positioning	Fixture shape positioning
Auto focus method	Side sensor positioning / ranging sensor positioning	Ranging sensor positioning	Ranging sensor positioning
Processing nameplate stations number	Single station	Multi-station	Multi-station
Laser power	20W	50W	100W
Unloading method	Single-station receiving and unloading	Multi-station receiving and unloading	Multi-station receiving and unloading
Electricity requirements	220V/ single-phase 50HZ/20A		
Dimension	1020x750x1900mm	1300x900x1600mm	2400x1050x1800mm
Special function	-	-	Grind and remove metal chips

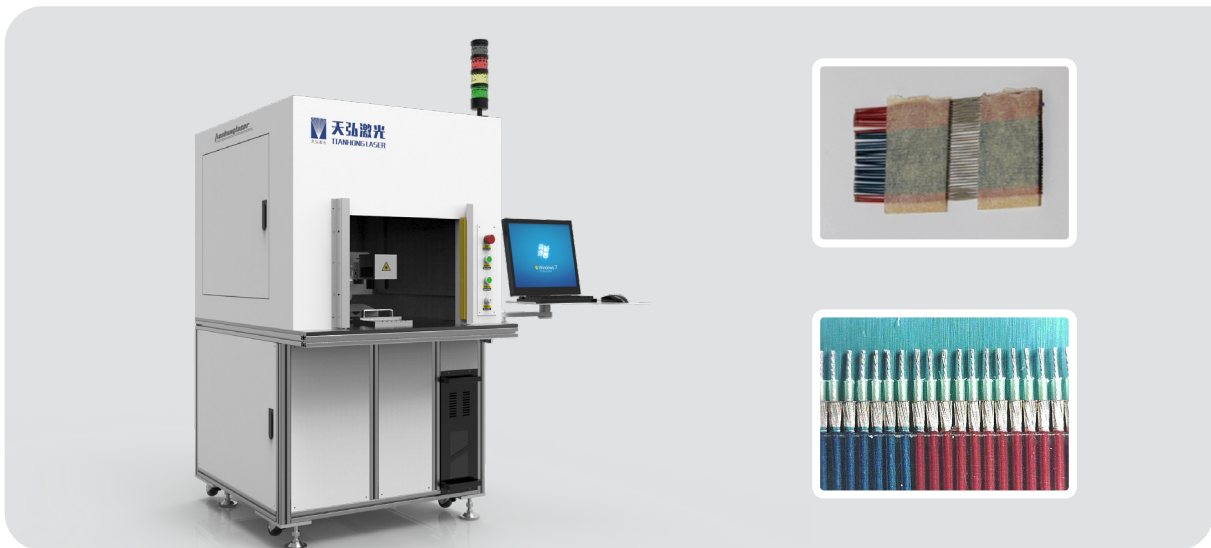
Laser Wire/Cable Stripping Machine

Features

- » Double light path design, simultaneous working on diagonal, efficient and practical;
- » Table belt synchronous transit, linked with laser power and stripping speed, ensuring high speed;
- » Software control, adjustable speed, which is with good stripping effect;
- » Designed for the electronic cable industry, it has compact structure, high reliability, powerful software functions, flexible operation, and is close to the production itself.
- » The equipment can be customized according to the actual needs of customers to achieve special purpose and improve efficiency.

Application field

CO2 laser wire stripping machine can strip non-metallic outer layer and insulating inner layer.
Fiber laser wire stripping machine can strip metal shields.



Technical Parameter

Model	TH-CO2LPS30/60/100	TH-FLPS20/30/50
Laser source	CO ₂	Fiber
Laser power	30/60/100w	50/100w
Input power	1200W	
Wavelength	10.6um	1064nm
Laser energy adjustment	10 ~ 100%	
Positioning accuracy	±0.01mm	

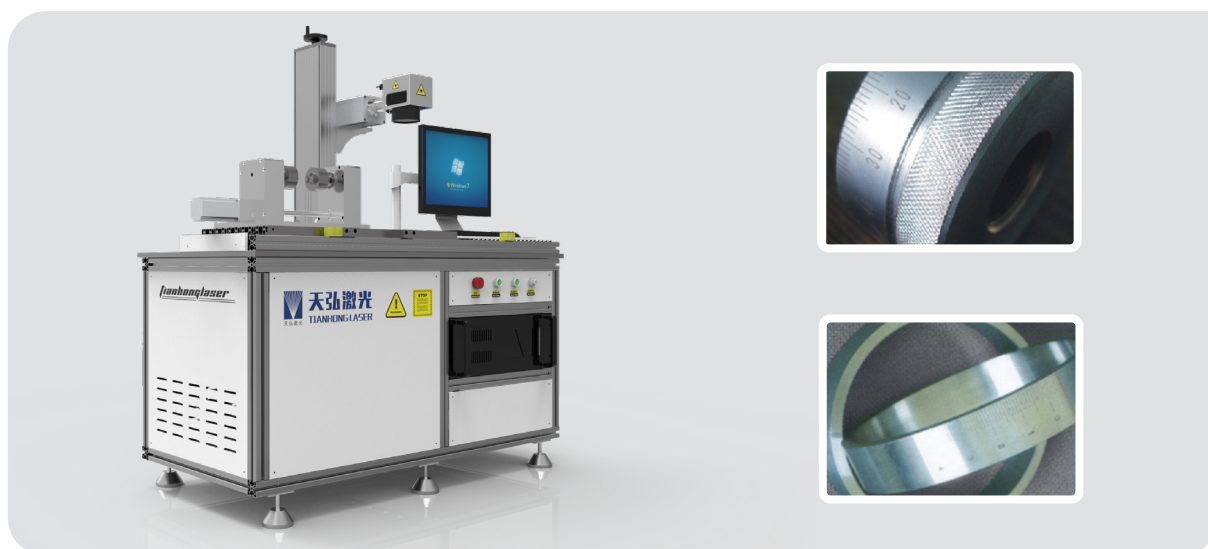
Cylindrical Laser Marking Machine

Features

- » Suitable for marking of continuous characters and logos on large angle work piece.
- » It can mark the character and logo 360 degree rotary.
- » Symmetrically marking, no distortion of projection.
- » Min.resolving capability of angle:360° /8000
- » Max. Load: 40KG

Application field

This equipment is designed for the medical industry and is used for the marking of precise angles, graduations, lead or stainless steel round surfaces.



Technical Parameter

Model	TH-Y2-FLMS
Laser power	20w/30w/50w/60w
Wavelength	1064nm
Clamping method	Three-jaw chuck
Drive mode	Servo motor +screw
Positioning accuracy	±0.05mm
Repetition accuracy	±0.01mm
Electricity requirement	220V/ single-phase 50A/20A
Processing range	100x100mm (optional)
Dimension	1500x600x1600mm

Bearing Laser Marking Machine

Features

- » Double cylinder, plane transmission positioning system synthesis.
- » Designed for high volume bearing marking.
- » Can be marked on the various specifications of bearing end face.
- » Effectively improve work efficiency and save manpower.

Application field

The equipment is designed for the mechanical bearing industry, with compact structure, high reliability, powerful software functions, flexible operation, and close to the production itself. It can be marked on a variety of bearing end face of different sizes to meet different needs.



Technical Parameter

Model	TH-ZC-FLMS
Laser power	20W/30W/50W
Marking range	175x175mm (optional)
Marking method	Single-sided / double-sided marking
Bearing outside diameter range	20-150mm (can be customized)
Positioning method	Side V-type IR Positioning / Both Side V-type Positioning Grip Positioning
Transmission method	Pipeline method / V-clamp positioning movement method on both sides
Marking position	One-sided arc marking at one or more places
Electricity requirement	220V/ single-phase 50HZ/20A
Dimension	Can be customized

Laser Cleaning Machine

Features

- » Portable and movable, no need to disassemble and carry.
- » Precise cleaning, light output width can be set.
- » Non-contact cleaning, almost no damage to the substrate surface.
- » No chemical cleaning solution, safe and environmentally friendly.

Application field

The equipment is used in the mold industry, automobile manufacturing, shipbuilding, food processing, sewage treatment, rubber tires, petrochemical and other industries. Can be used for metal surface rust removal; surface paint removal and paint removal; surface oil, stain, dirt cleaning; surface coating, coating removal; welding surface/spray surface pretreatment; stone statue surface dust and attachment removal; rubber mold residue cleaning etc.



Technical Parameter

Model	TH-LC-100D-A	TH-LC-200D-A	TH-LC-300D-A	TH-LC-500D-A
Laser power	100w	200w	300w	500w
Laser type	Fiber Laser			
Wavelength	1064nm			
Cooling method	Air cooling/ water cooling			
Water temperature	18-25°C			
Cabinet dimension	575x400x500mm	610x500x700mm	640x540x730mm	850x830x960mm
Machine weight (include water tank)	39.5kg	52kg	54kg	120kg
Power consumption	800W	1400W	1600W	1800W
Focus depth	3mm	5mm	10mm	15mm
Scanning width	2-50mm			
Auxiliary gas	Compressed air / nitrogen			
Air pressure	0.5-0.8Mpa			
Optional configuration	Hand-held			
Working environment temperature	5-40°C			

Mini Laser Marking Machine

Features

- » Flexible and lightweight, suitable for daily home, office and other marking needs.
- » Easy to operate, connect a personal computer to export graphic data to achieve instant marking.
- » The whole machine is small in size, light in weight and easy to move.

Application field

It is mainly used for the marking of metal signs, as well as the laser coding of color paper and other products, to meet the needs of daily creative design.



Technical Parameter

Model	OLM-20
Wavelength	1064nm
Laser	Totally enclosed (double-clad) fiber pulsed laser
Power	20w
Cooling way	Air cooling
Output power	≥ 20w
Marking range	100x100mm optional
Positioning accuracy	±0.03μm
Min. Line width	0.045mm (depending on material) @ F=160 mm
Single point energy	1mj
Beam quality	≤ 1.2
Pulse width	≤ 100ns
Pulse repetition frequency	20-200kHz
Engraving speed	≤ 7000mm/s
Degree of protection	IP54

Five Axis 3D Marking System (LDS)

Features

» Using the control system to control the movement of the laser according to the trajectory of the electronic circuit, put the laser on the injection-molded three-dimensional plastic device, and activate the material with the laser in a short time because The laser separates (laser activation) the metallographic compounds in the dopant-containing plastic. The exposed metal atoms after laser activation are used as the seed layer of the electroless plating process. During the electroless plating process, a metal layer (surface metallization) with a thickness of 5-10 microns can be grown in the activated area to realize the formation of three-dimensional circuits of the material.

Application field

Widely used in mobile communications, IoT projects, automotive IoT components, Industry 4.0, and medical industries.



Technical Parameter

Model	TH-FLCS30	TH-FLCS50	TH-FLCS100
Laser average output power	30W	50W	100W
Wavelength	1064nm		
Pulse width	2—350ns		
Laser repetition frequency	1KHz—4000KHz		
Engraving range	100mm×100mm×40mm、300×300×200 (optional)		
Engraving line speed	≤ 7000mm/s		
Min. width	0.015mm		
Repetition accuracy	≤ 0.005mm		
XYZ motion module accuracy	±0.01mm		
Power consumption	1500W		
Electrical requirement	220V±22V / 50Hz/ 10A		
Dimension	1150mm×1360mm×2000mm		
Weight	750Kg		

Laser Resistor Trimming System

Features

- » High trimming accuracy and high repetition accuracy.
- » High stability and reliability, can work for a long time.
- » Automatic loading and unloading can be customized, automatic coding, automatic trimming and automatic verification.

Application field

Mainly applied for circuit micro adjustment of thick/ thin electronic board. Widely used for thick film hybrid intergrated circuits, electronic components, auto circuit, sensor, military scientific research, chips resistor, etc.



Technical Parameter

Model	TH-FLCS20
Processing method	Galvanometer processing
Platform moving travel	400mm
Laser source	Pulse laser 1064nm
Trimming accuracy	±1%
Laser output max. power	20w
Focus method	Manual adjustment
Platform positioning accuracy	±0.05mm
Processing positioning method	CCD
Operation environment	+15°C ~-30°C
Dimension	1000x700x1500mm

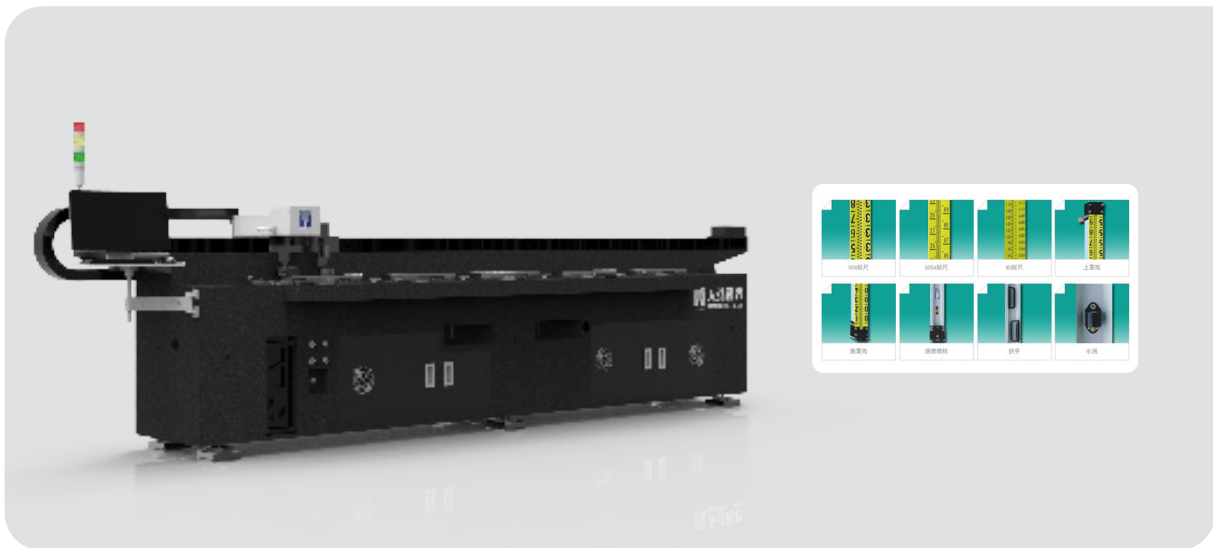
Invar Laser Processing System

Features

- » Customized standard of bar code layout.
- » Marking, measuring and checking.

Application field

Leveling/Rulers, such as Zeiss, Topcon, etc.



Technical Parameter

Model	TH-IV3000
Scale length	2m/3m
Marking accuracy	$\pm 5\mu\text{m}/3000\text{mm}$
Marking time	1H/piece(3m)
Positioning method	CCD
Detection accuracy	$\pm 10\mu\text{m}/3000\text{mm}$
Half tolerance	700kg

ENTERPRISE HONOR



National High-tech Enterprises



Suzhou Gazelle Enterprises



Jiangsu Province Science and Technology Innovation Enterprise



2018 Outstanding Economic Contribution Award



Advanced Collective of Intellectual Property Work



Top 10 Brands Award of Lijia Cup 2018



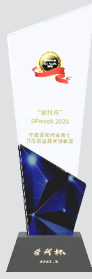
Suzhou Top 100 Enterprises



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China Laser Processing System Innovation Contribution Award Technology Enterprise



"OF week" Technology Innovation Award



Huaxing Award Best Innovation



China Outstanding Progressive Laser Enterprise Award

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103

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■ If you need to know more about our company, or have better suggestions for company's development, please let us know by phone, fax or email. We will respond or contact you after understand your needs.

Note: the quotation marked with * should correspond to the configuration required by the actual technical proposal.

Stock Code: **430549**